



US00D586812S

(12) **United States Design Patent**
Guenther

(10) **Patent No.:** **US D586,812 S**
(45) **Date of Patent:** **** Feb. 17, 2009**

(54) **ELECTRONIC SIGNATURE PAD**

DE 10 2006 000 859 A1 7/2007

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(**) Term: **14 Years**

(21) Appl. No.: **29/293,029**

(22) Filed: **Nov. 7, 2007**

(30) **Foreign Application Priority Data**

May 8, 2007 (DE) 4 07 02 450

(51) **LOC (9) Cl.** **14-02**

(52) **U.S. Cl.** **D14/383**

(58) **Field of Classification Search** D14/341-346,
D14/383-387; D18/4.4, 4.6, 6, 7; 382/115,
382/116, 119, 124, 126; 346/71; 235/382,
235/382.5; 345/169, 173; 361/681-686
See application file for complete search history.

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(57) **CLAIM**

The ornamental design for an electronic signature pad, as shown and described.

DESCRIPTION

FIG. 1 is a perspective view of an electronic signature pad of the present invention;

FIG. 2 is a front elevational view of the electronic signature pad;

FIG. 3 is a back elevational view of the electronic signature pad;

FIG. 4 is a top plan view of the electronic signature pad;

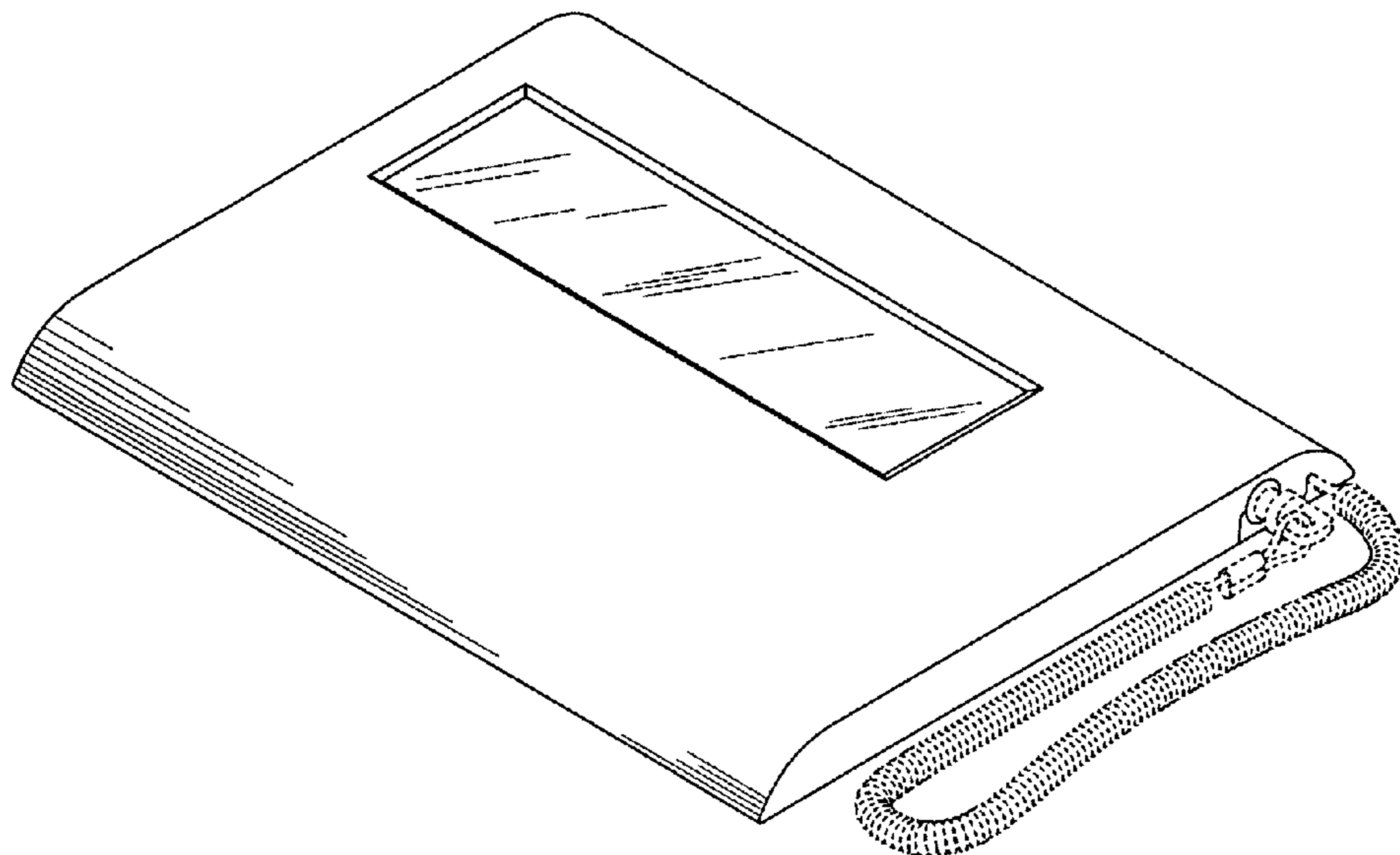
FIG. 5 is a bottom plan view of the electronic signature pad;

FIG. 6 is a right side elevational view of the electronic signature pad; and,

FIG. 7 is a left side elevational view of the electronic signature pad.

The broken lines shown are for illustrative purposes only and form no part of the claimed design.

1 Claim, 7 Drawing Sheets



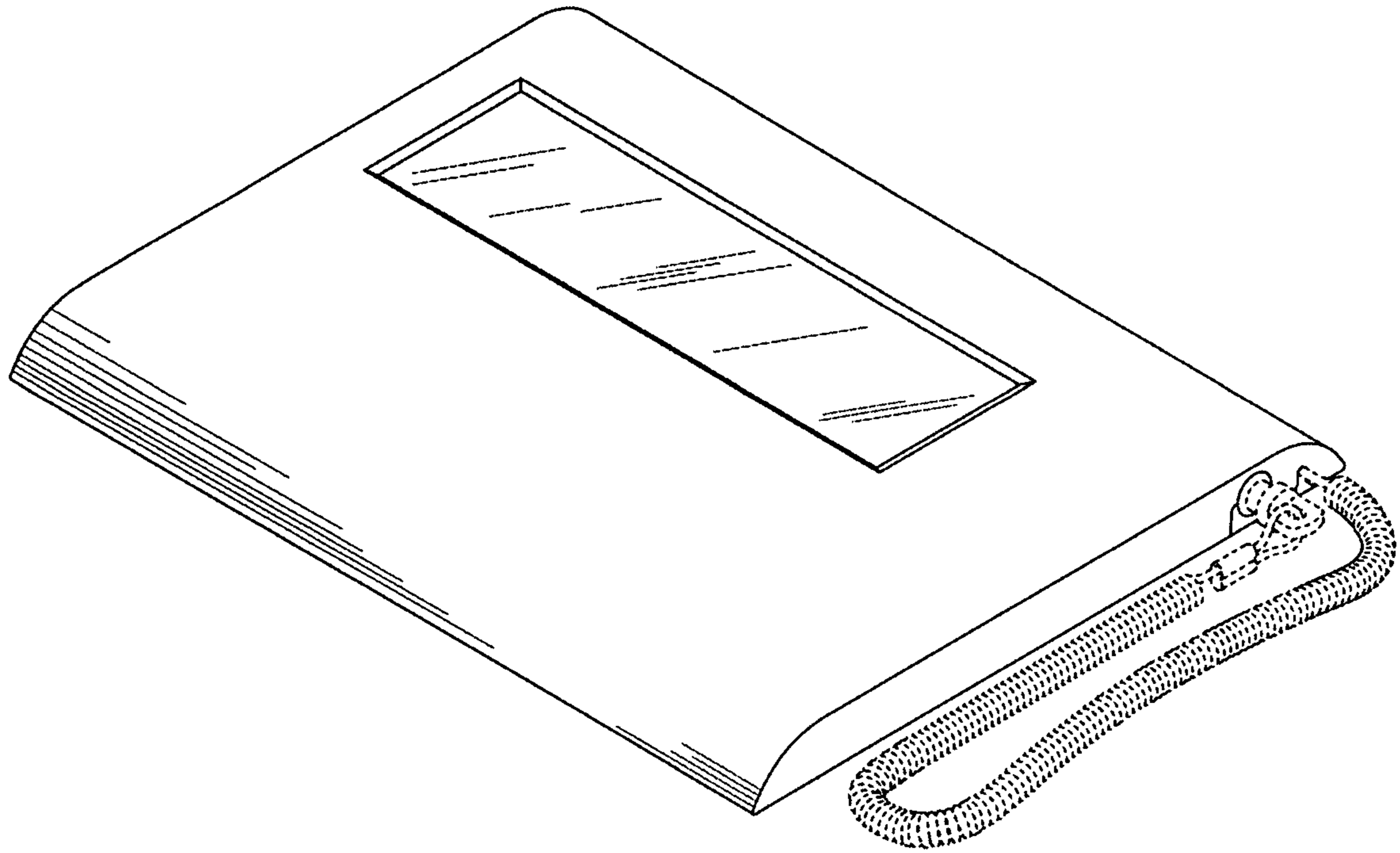


Fig. 1

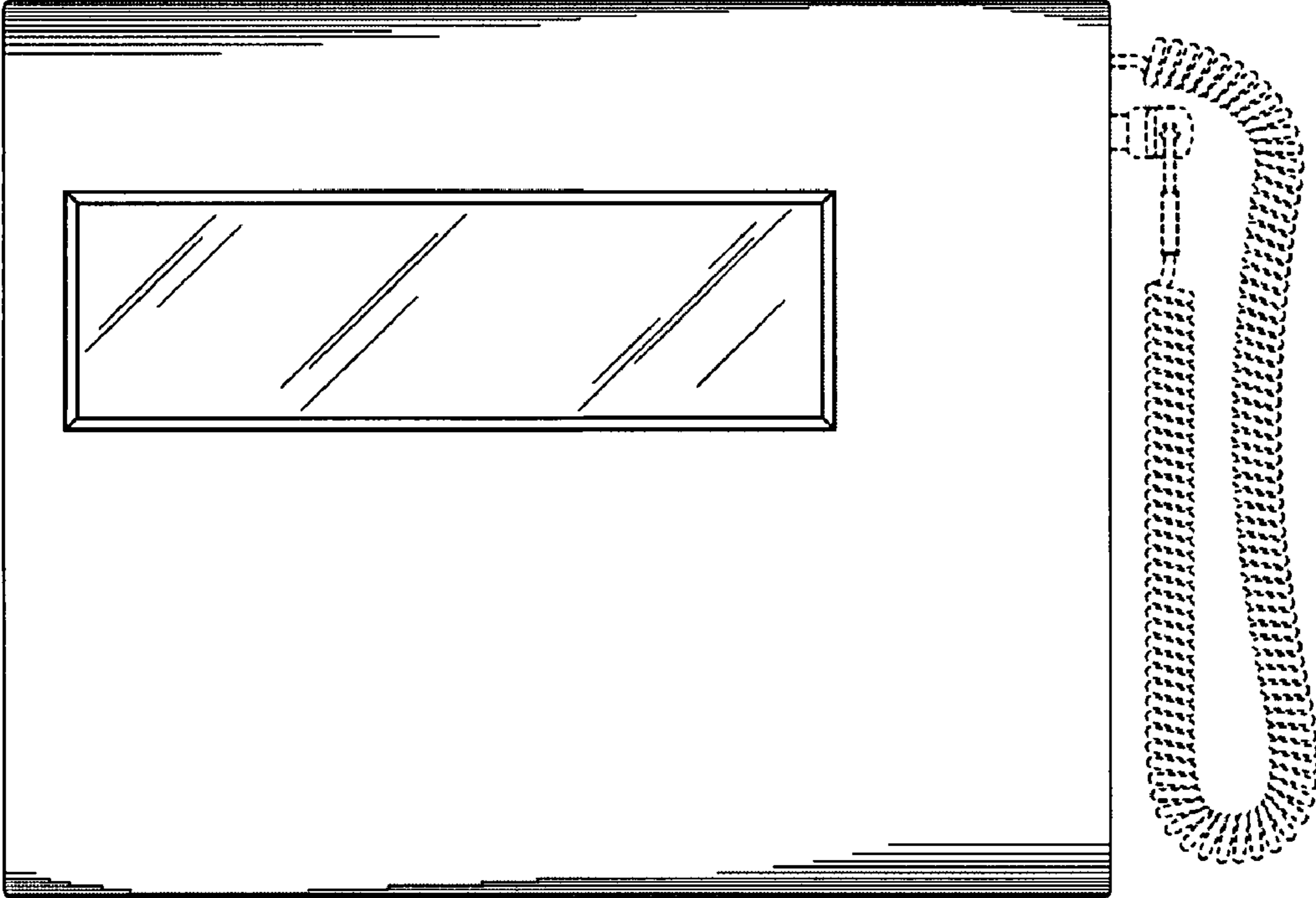


Fig. 2

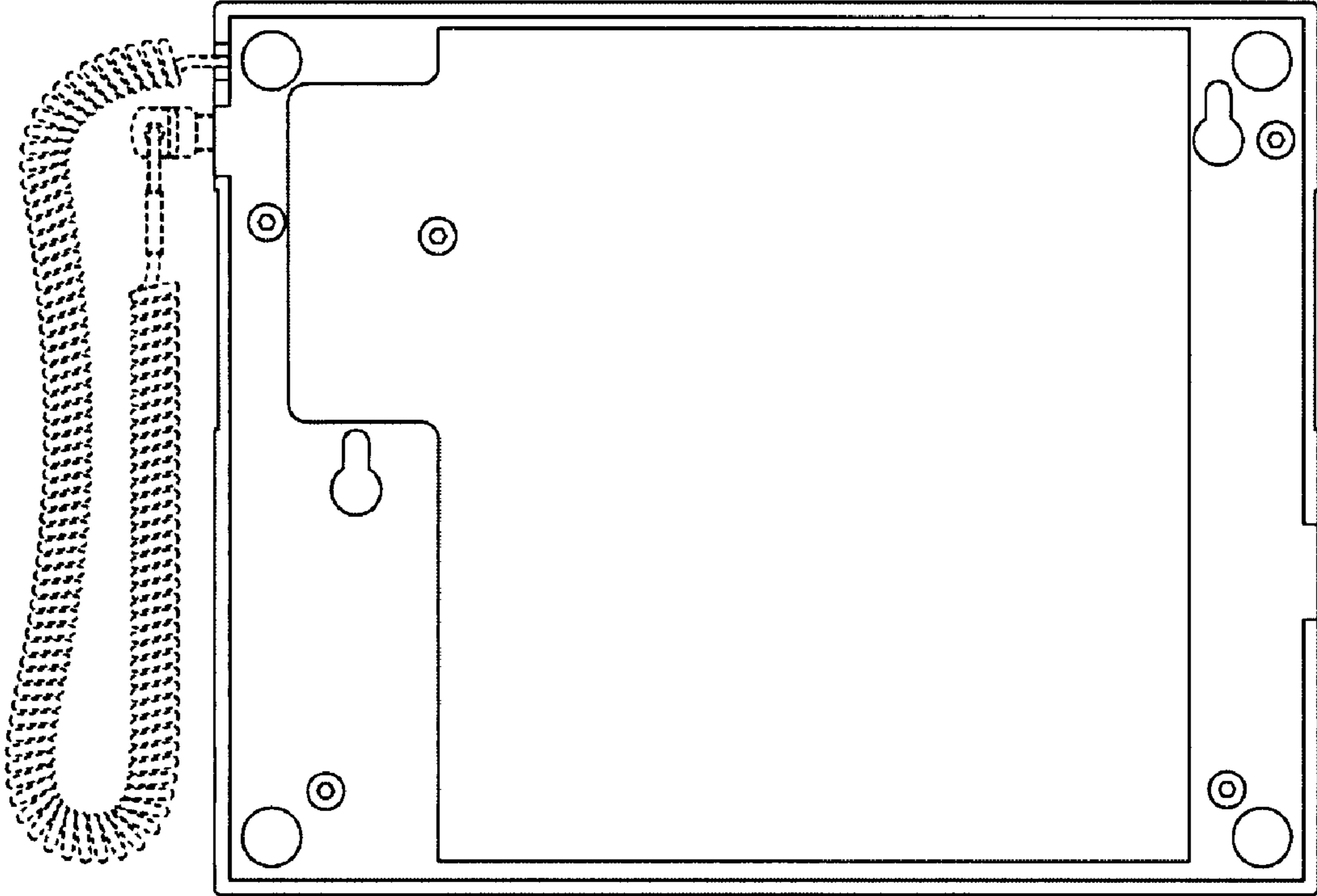


Fig. 3



Fig. 4

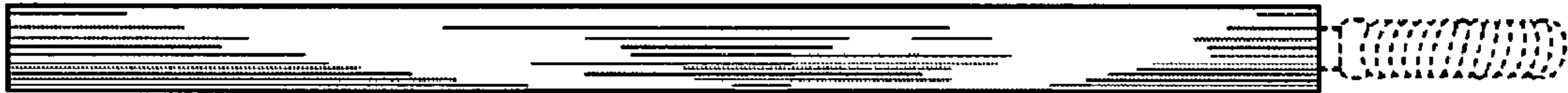


Fig. 5



Fig. 6

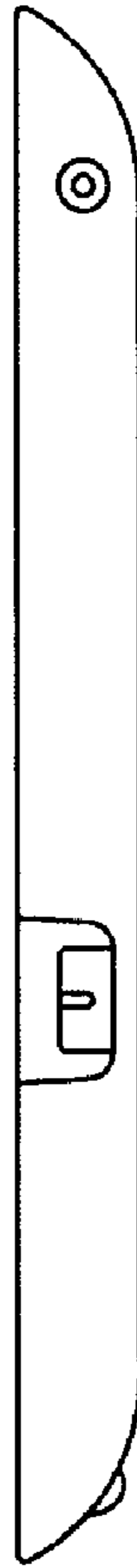


Fig. 7